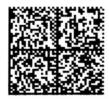
PCN Number:				2	20230406002.1							F	PCN Date:	April	11, 2023		
Title: Qualification			of	of ASEN as Additional Assembly Site for Select Package Devices							· ·						
					CN Manage					,							
Customer Contact:			_	Sample reques				te									
									ā	acc	epted u	ntil:	May 11, 2023*				
	*Sample requests received after "May 11, 2023" will not be supported.																
	Change Type:         ☑ Assembly Site       ☑ Design       ☐ Wafer Bump Material								- wie l								
			rocess			누		Design Data S		ot [			╣	Wafer Bump Material Wafer Bump Process			
X						Ė		Part number change			Wafer Fab Site						
	<ul><li>✓ Assembly Materials</li><li>✓ Mechanical Specific</li></ul>				ion	Ī		Test Site					als				
M	Pack	ing/Sh	ipping/L	_ab	eling		Test Process ☐ Wafer Fab Proce					Proces	SS				
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			s follow		u III tile	FIC	Juu	ICC AII	ecteu	36	ection. C	Juilei	IL	assembly si	tes an	u Materiai	
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Ass	embly		Assemi		Site Origi	n	Α	ssemb		Country Code			Assembly Site City				
	UTAC				SE				THA					Bangkok			
	ASEN			A	SN				CHN	<u> </u>			Suzhou				
Mate	erial I	Differe	ences:														
					UTAC ASEN												
M	1old C	ompou	ınd		CZ0138			1801512111									
Reas	on fo	r Cha	nge:														
Cont	inuity	of sup	ply.														
Antio	cipate	ed imp	pact on	F	orm, Fit,	Fu	ınc	tion,	Qual	ity	or Relia	bility	y (	(positive /	nega	tive):	
None	None																
Im pa	Impact on Environmental Ratings:																
Che	cked	boxes	indicate	e tl	he status	of	en	vironn	nental	rat	tinas foll	ow inc	ı c	mple ment at	ion of	this	
change. If below boxes are checked, there are no changes to the associated environmental ratings.																	
RoHS				R	СН	CH Green Sta						IEC 62474					
				⊠ No Change ⊠ No Change						⊠ No Change							
Changes to product identification resulting from this PCN:																	
Assembly Site					A					ACO: NCE							
UTAC					Assembly Site									ASO: N			
ASEN				Assembly Site Origin (22L)					ASO: ASN								
Samp	Sample product shipping label (not actual product label)																



MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

(L)T0:3750



(1P) SN74LS07NSR

(Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS (2P) REV:

### **Product Affected:**

TPS3420ADDRYR	TPS3420DDRYR	TPS3420DDRYT	TS3A4751RUCR
I I JJTZUADDIKI K	I I JJTZUDDIKI K	II JJTZUDDINI I	1 JJAT/ JINOCK

# **Qualification Report**

Approved Date 05-April-2023

### **Product Attributes**

Attributes	Qual Device: TPS3420DDRYR	Qual Device: TS3A4751RUCR		
Assembly Site	ASEN	ASEN		
Package Family	USON	X2QFN		
Package Designator	DRY	RUC		
Wafer Fab Supplier	MH8	FR-BIP-1		
Flammability Rating	UL 94 V-0	UL 94 V-0		

Qual Device TPS3420DDRYR is qualified at MSL1-260C Qual Device TS3A4751RUCR is qualified at MSL1-260C

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS3420DDRYR	Qual Device: TS3A4751RUCR
PC	Preconditioning	Level 1 - 260C	3/693/0	3/231/0
UHAST	Unbiased HAST, 130C	96 Hours	3/231/0	
SAM	Post Unbiased HAST SAM	Devices	3/15/0	
BHAST	Biased HAST, 130C	96 Hours	3/231/0	
SAM	Post Biased HAST SAM	Devices	3/15/0	
TC	Temperature Cycle, -55C/125C	700 Cycles	3/231/0	
SAM	Post Temperature Cycle SAM	Devices	3/15/0	
TC	Temperature Cycle, -65C/150C	500 Cycles		3/231/0
SD	Solderability, Pb-Free	155C Dry Bake	3/66/0	3/66/0
SD	Solderability, Pb	155C Dry Bake	***	3/66/0
MQ	Manufacturability (Assembly)	(per mfg site requirements)	3/PASS	3/PASS
DSS	Die Shear Strength	Die	3/30/0	3/30/0
BBS	Ball Bond Shear	Ball Bonds	3/228/0	3/228/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0
PD	Physical Dimensions	(per pkg drawing requirements)	3/60/0	3/60/0
CHAR	Electrical Characterization	(per datasheet specifications)	1/30/0	1/30/0
MSL	Moisture Sensitivity Level	Level 1 - 260C	3/36/0	
YLD	FTY and Bin Summary	Lots	3/PASS	3/PASS

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and - 65C/150C/500 Cycles

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

Quality and Environmental data is available at TI's external Web site: http://www.ti.com

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail					
WW PCN Team	PCN ww admin team@list.ti.com					

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